

**IN THE SPECIFICATION:**

Please replace the first full paragraph of specification page 1, in the Cross-Reference to Related Applications section, with the following replacement paragraph:

The present application is a continuation-in-part of commonly assigned ~~copending~~ granted U.S. Patent ~~Application Serial No. 09/823,600~~ 6,891,257 B2, which was ~~filed~~ issued on ~~March 30, 2001~~ May 10, 2005, by David Chong, et al. for a PACKAGING SYSTEM FOR DIE-UP CONNECTION OF A DIE-DOWN ORIENTED INTEGRATED CIRCUIT and is hereby incorporated by reference.

Please add, after the first full paragraph of specification page 1, in the Cross-Reference to Related Applications section, the following paragraph:

The present application is related to the commonly assigned copending U.S. Patent Application Serial No. 10/835,212, of common ownership, which was filed on April 29, 2004, by Jeff Kingsbury, et al., for a SINGLE ROW BOND PAD ARRANGEMENT, and is hereby incorporated by reference.